NOW PART OF

Reliability Data Report
Product Family R570

LT3001 \ LT3002 \ LT3905 \ LT8210 / LT8253 \
LT8300 \ LT8301 \ LT8302 \ LT8303 \ LT8304 \
LT8309 \ LT8315 \ LT8316 \ LT8330 \ LT8331 \
LT8335 \ LT8336 \ LT8337 \ LT8361 \ LT8362 \
LT8364 \ LT8365 \ LT8386 \ LT8390 \ LT8391 \
LT8392 \ LT8550 \ LT8601 \ LT8602 \ LT8603 \
LT8606 \ LT8607 \ LT8608 \ LT8609 \ LT8610 \
LT8611 \ LT8612 \ LT8613 \ LT8614 \ LT8616 \
LT8619 \ LT8620 \ LT8640 \ LT8641 \ LT8642 \
LT8672 \ LT8697 \ LT8711

Reliability Data Report
R570

Report generated on: Fri May 21, 2021

• OPERATING LIFE TEST

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C)	No. of FAILURES
SOIC/MSOP	46,902	1206	1648	13,491	0
QFN/DFN	14,042	1112	1651	12,681	0
SOT	1,078	1206	1502	3,600	0
LGA	2,262	1842	2048	4,543	0
SSOP/TSSOP	231	1525	1613	643	0
Totals	64,515			34,958	0

• BIASED HIGHLY ACCELERATED STRESS TEST AT +130°C/85%RH

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+85°C)	No. of FAILURES
SOIC/MSOP	1,776	1318	1646	4,535	0
QFN/DFN	7,868	1117	1706	19,044	0
SOT	1,738	1141	1708	5,833	0
LGA	4,118	1842	2048	12,385	0
SSOP/TSSOP	774	1526	1639	2,367	0
Totals	16,274			44,164	0

• PRESSUR COOKER TEST AT 15 PSIG , +121 DEG C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
SOIC/MSOP	26,994	1239	1715	1,849	0
QFN/DFN	18,766	0227	1714	1,865	0
SOT	2,180	1302	1710	295	0
SSOP/TSSOP	383	1504	1608	103	0
Totals	48,323			4,112	0

• TEMPERATURE CYCLE FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/MSOP	28,016	1240	1713	10,142	0
QFN/DFN	32,338	0227	1712	21,344	0
SOT	3,060	1141	1710	2,298	0
LGA	12,128	1842	2048	8,051	0
SSOP/TSSOP	858	1526	1639	1,410	0
Totals	76,400			43,245	0

• THERMAL SHOCK FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
SOIC/MSOP	26,006	1240	1715	7,492	0
QFN/DFN	18,206	0227	1714	11,296	0
SOT	2,140	1141	1710	798	0
LGA	931	1850	2009	1,288	0
SSOP/TSSOP	310	1526	1608	392	0
Totals	47,593			21,266	0

• HIGH TEMPERATURE BAKE +150°C					
PACKAGE TYPE	**SAMPLE SIZE**	**OLDEST DATE CODE**	**NEWEST DATE CODE**	**K DEVICE HRS**	**No. of FAILURES**
SOIC/MSOP	1,546	1308	1526	1,834	0
QFN/DFN	4,882	1425	1704	5,132	0
SOT	200	1611	1625	400	0
LGA	1,965	1848	2048	2,798	0
SSOP/TSSOP	288	1622	1642	576	0
Totals	8,881			10,740	0
• HIGH TEMPERATURE BAKE +125°C					
PACKAGE TYPE	**SAMPLE SIZE**	**OLDEST DATE CODE**	**NEWEST DATE CODE**	**K DEVICE HRS**	**No. of FAILURES**
QFN/DFN	200	1550	1550	4	0
Totals	200			4	0
• HIGH TEMPERATURE BAKE +175°C					
PACKAGE TYPE	**SAMPLE SIZE**	**OLDEST DATE CODE**	**NEWEST DATE CODE**	**K DEVICE HRS**	**No. of FAILURES**
SOIC/MSOP	2,392	1325	1640	2,342	0
QFN/DFN	3,266	0227	1550	3,267	0
SSOP/TSSOP	231	1526	1508	231	0
Totals	5,889			5,840	0

(1) Assumes Activation Energy = 0.7 Electron Volts
(2) Failure Rate Equivalent to +55°C, 99% Confidence Level = 1.76 FITS
(3) Mean Time Between Failure in Years : 64909.27
Note 1: 1 FIT = 1 Failure in One Billion Hours
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL Preconditioning